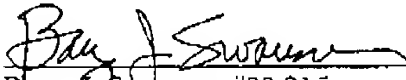


This constitutes a request for any needed extension of time and an authorization to charge all fees therefore to deposit account No. 19-5117, if not otherwise specifically requested. The undersigned hereby authorizes the charge of any fees created by the filing of this document or any deficiency of fees submitted herewith to be charged to deposit account No. 19-5117.

Respectfully submitted,

Date: Nov. 25, 2002

  
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Marked up version showing changes to claims under 37 C.F.R. § 1.121(c)(ii)

1. (twice amended) A method for the manufacture of a freestanding segmented nanoparticle by the deposition of a plurality of materials inside a template, comprising:
  - a) causing deposition of a first material into a pore of said template;
  - b) causing deposition of a second material into said pore of said template, wherein the deposition of at least one of said first material and said second material is electrochemical deposition; and
  - c) releasing said segmented nanoparticle from said template to provide a freestanding segmented nanoparticle having a length from 10 nm to 50  $\mu$ m and a width from 5 nm to 50  $\mu$ m, wherein said freestanding segmented nanoparticle comprises 50 or fewer segments.
3. (amended) The method of claim [2] 1 wherein said segmented nanoparticle [is comprised of 2-50 segments, wherein the particle] has a length [is] from 1-15  $\mu$ m[, the particle] and a width [is] from 30 nm to 2  $\mu$ m[, and the length of said segments is from 50 nm to 15  $\mu$ m].
9. (amended) The method of claim [8] 1 wherein an electrode is placed on or in proximity to one surface of said template, and said template is placed in contact with a first plating solution to deposit said first material, and is placed in contact with a second plating solution to deposit said second material.

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